



志聖工業

C SUN MFG Inc.,

Investor Meeting, Citi Corporate Day 2025



合力共創 同行致遠



G2C+

T STRATEGY ALLIANCE

GPM 均豪

c sun 志聖

GMM 均華

Market Leader

Close to leading
Customers

Technological
Innovation

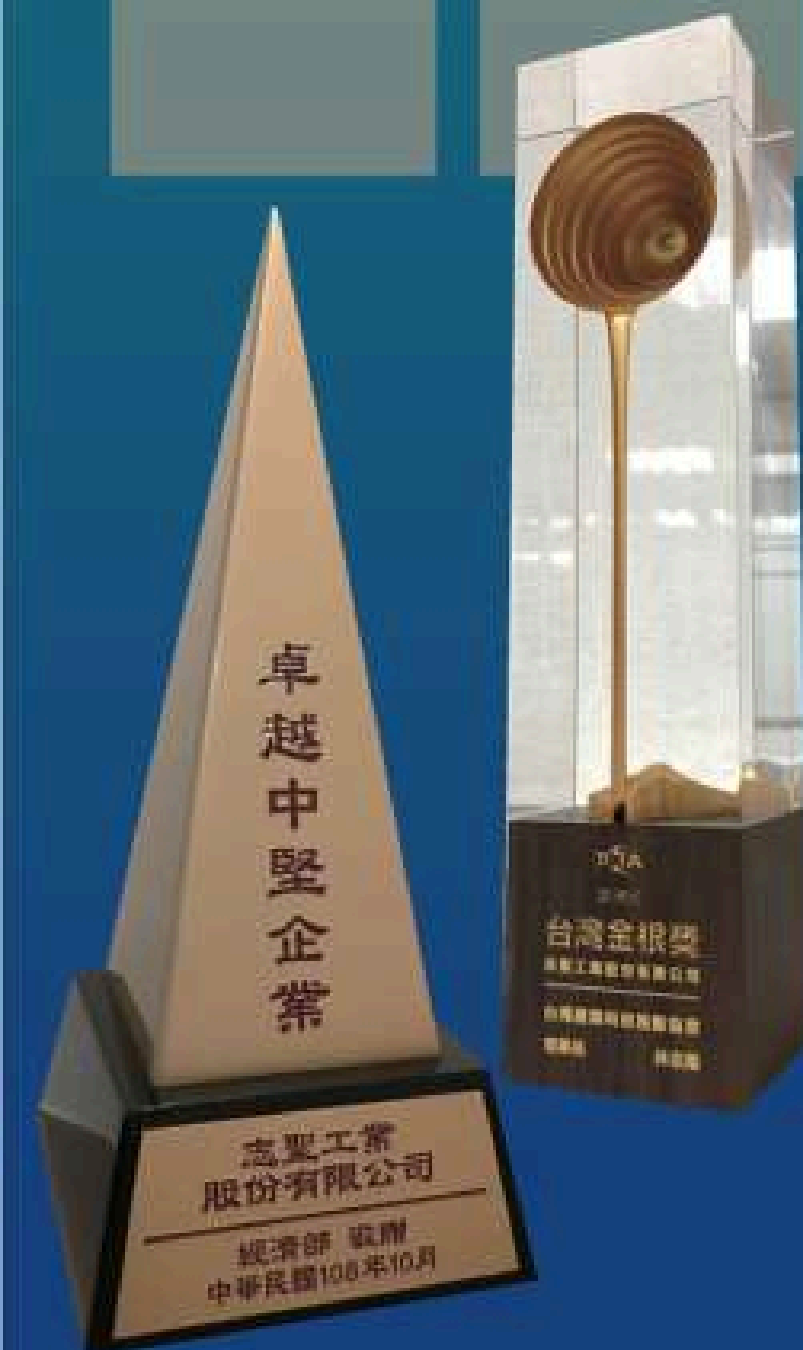
『 Management is Coordination 』

--- Dr. Dah-Hsian Seetoo ---

『 The New Paradigm Shift 』

Competition oriented	➡	Co-prosperity & symbiosis
Barrier shielding	➡	Alliance & Sharing
Product Service	➡	Eco-system Value Creating
Single Play	➡	Leverage

--- Dr. Yi-Chia Chiu ---



The Alliance Members: 1700+



R&D personnel: 570+

R&D personnel account for 32.5%



***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

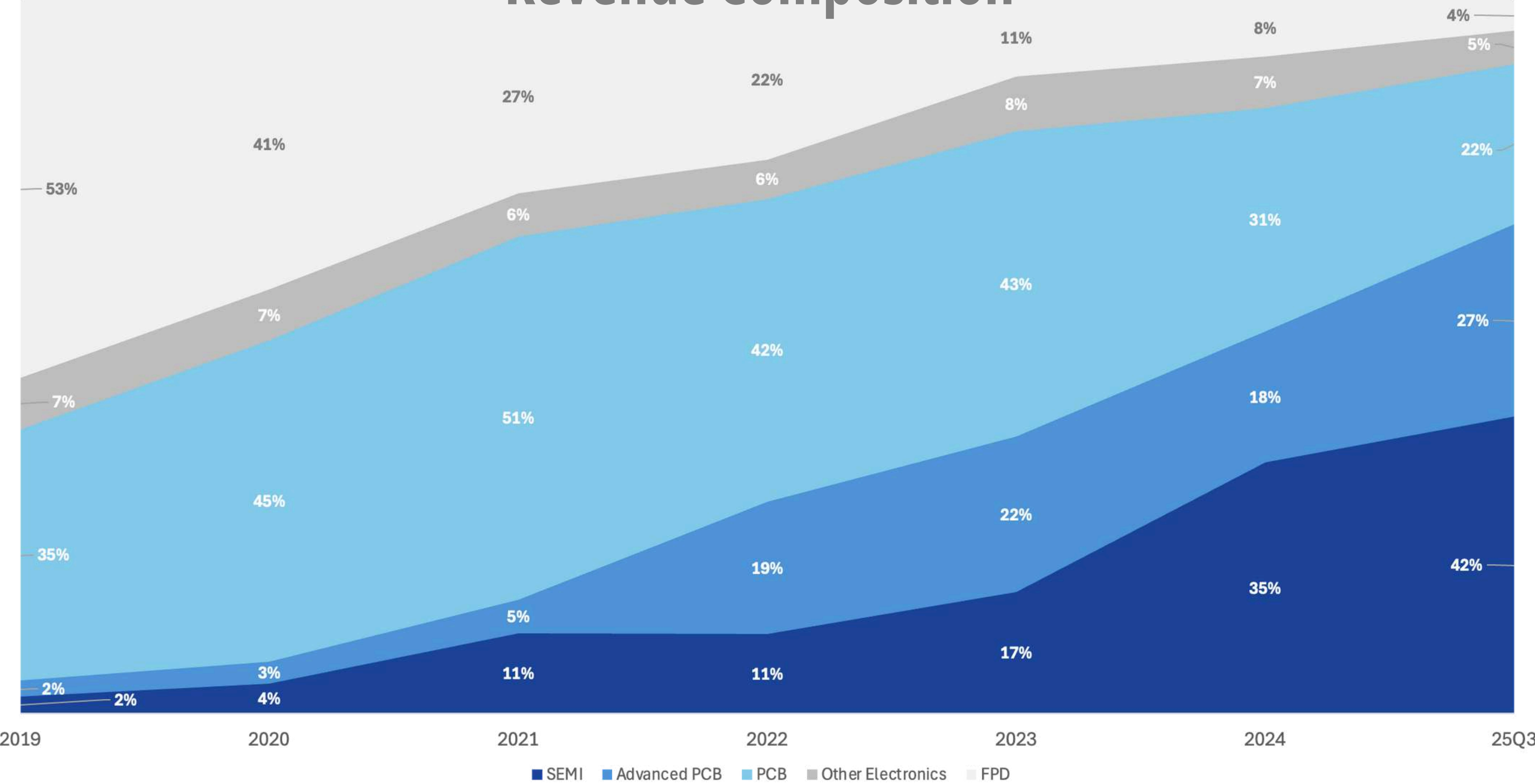
AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

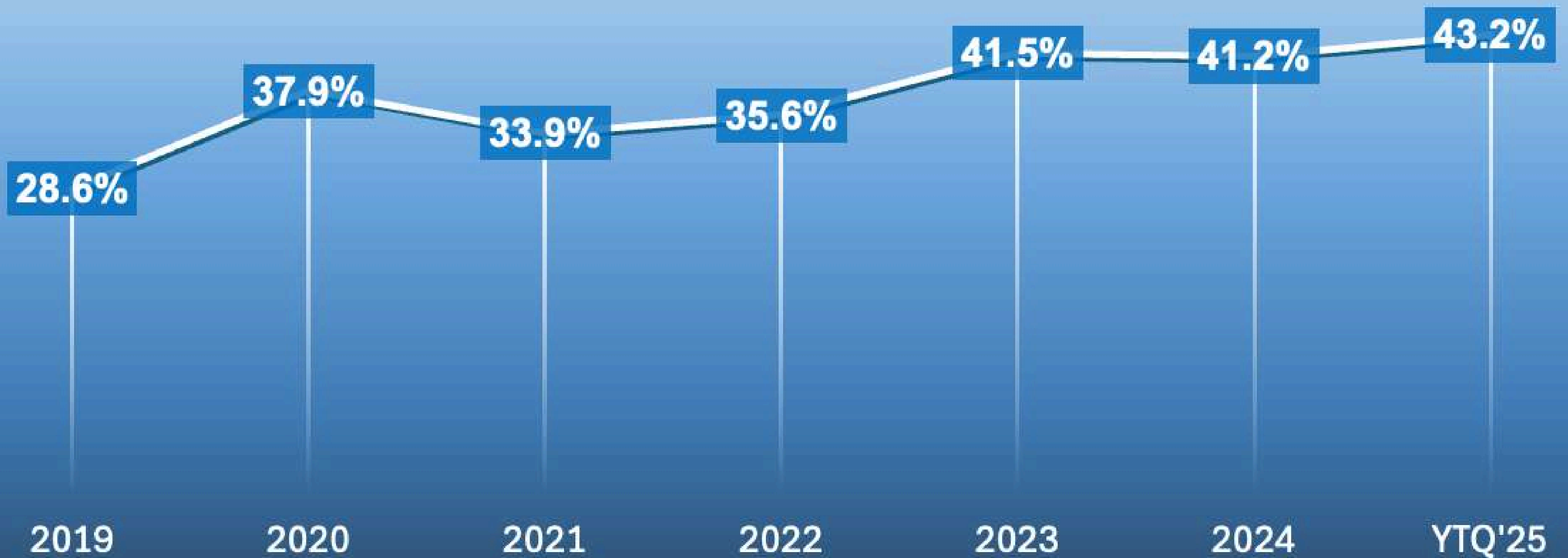
Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

Core Technologies & Alliance Synergy

Revenue Composition



Gross Margin Rate



Financial Results Summary					
<i>Selected Items from Statements of Comprehensive Income</i> <i>(In NT\$ millions unless otherwise noted)</i>					
	3Q25	2Q25	3Q24	QoQ	YoY
Revenue-Consolidated	1,536	1,510	1,054	1.7%	45.8%
Gross Margin%	44.2%	41.8%	42.2%	+2.4ppts	+2.0ppts
Operating Expense	(526)	(358)	(364)	47.0%	44.7%
Operating Expense%	34.3%	23.7%	34.5%	+10.6ppts	-0.2ppts
Operating Margin%	10.0%	18.1%	7.7%	-8.1ppts	+2.3ppts
Non-Operating Items	134	(5)	117	2411%	14%
Net Income Attributable to Shareholders of the Parent Company	212	207	165	2%	28%
Net Profit Margin%	13.8%	13.7%	15.7%	+0.1ppts	-1.9ppts
EPS (NT\$D)	1.4	1.37	1.1	2%	27%

SPANNING THE AI INDUSTRY

AI CHIP HPC

IC SUBSTRATE

- Lamination
- Vacuum Lamination
- ABF Peeler

Substrate

HBM

HBM PACKAGING

- Auto Oven

ADVANCED PACKAGING

2.5D/ 3DIC

Chip-on-Wafer-on-Substrate

- Lamination
- Bonder
- Auto Oven
- UV Cure

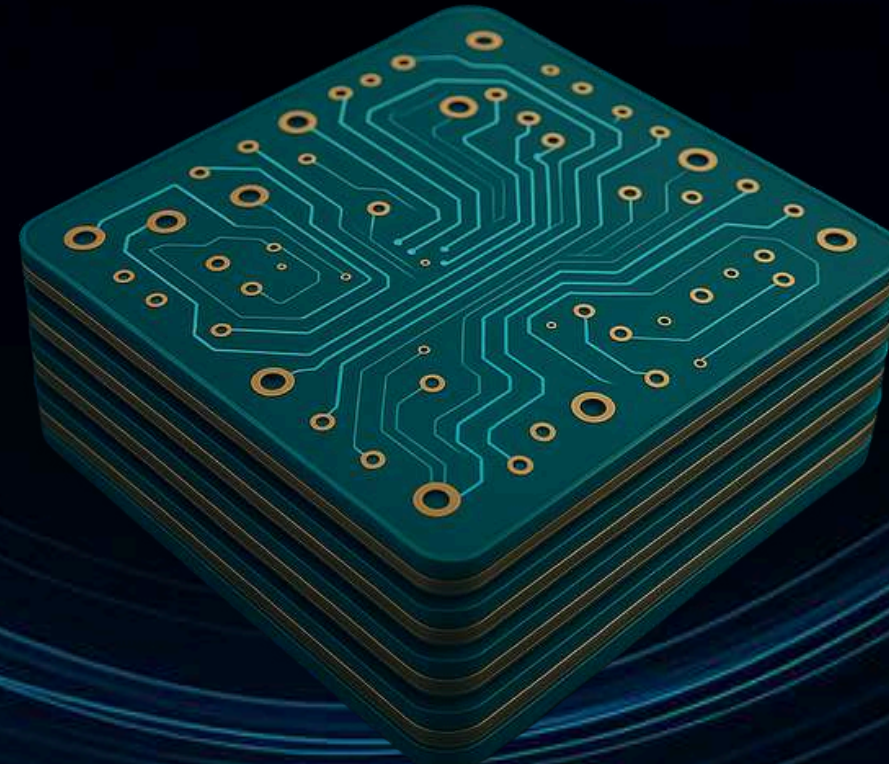


HDI PCB Demand from CPU, OAM to UBB and More

Auto Oven



Horizontal Immersion Tin
Equipment



c sun 志聖 **tcf** 創峰
TOP CREATION



Half Etching
Equipment

Auto-Peeler



Lamination



Pre-treatment
Equipment



乘勢而上的AI浪潮

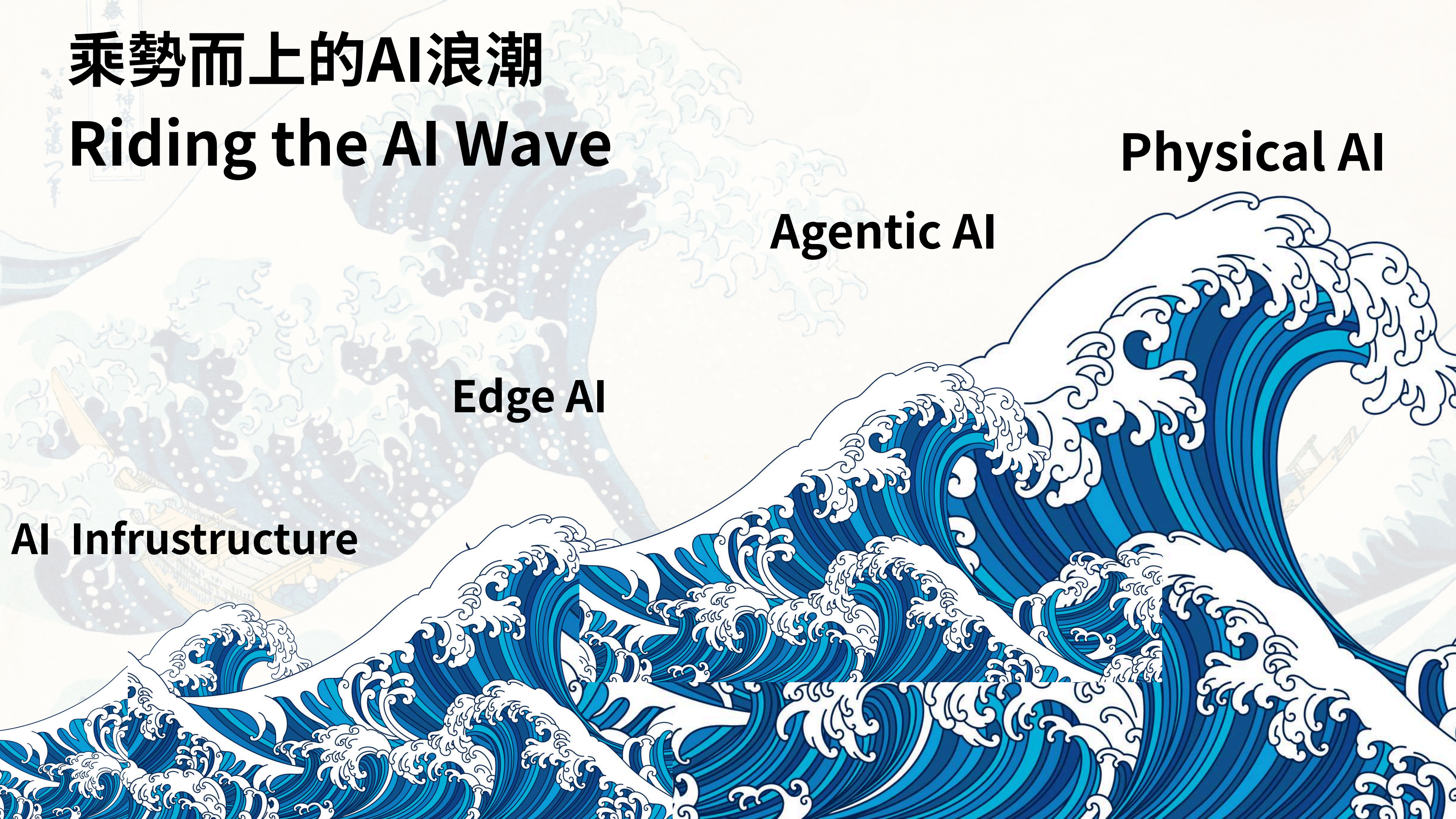
Riding the AI Wave

Physical AI

Agentic AI

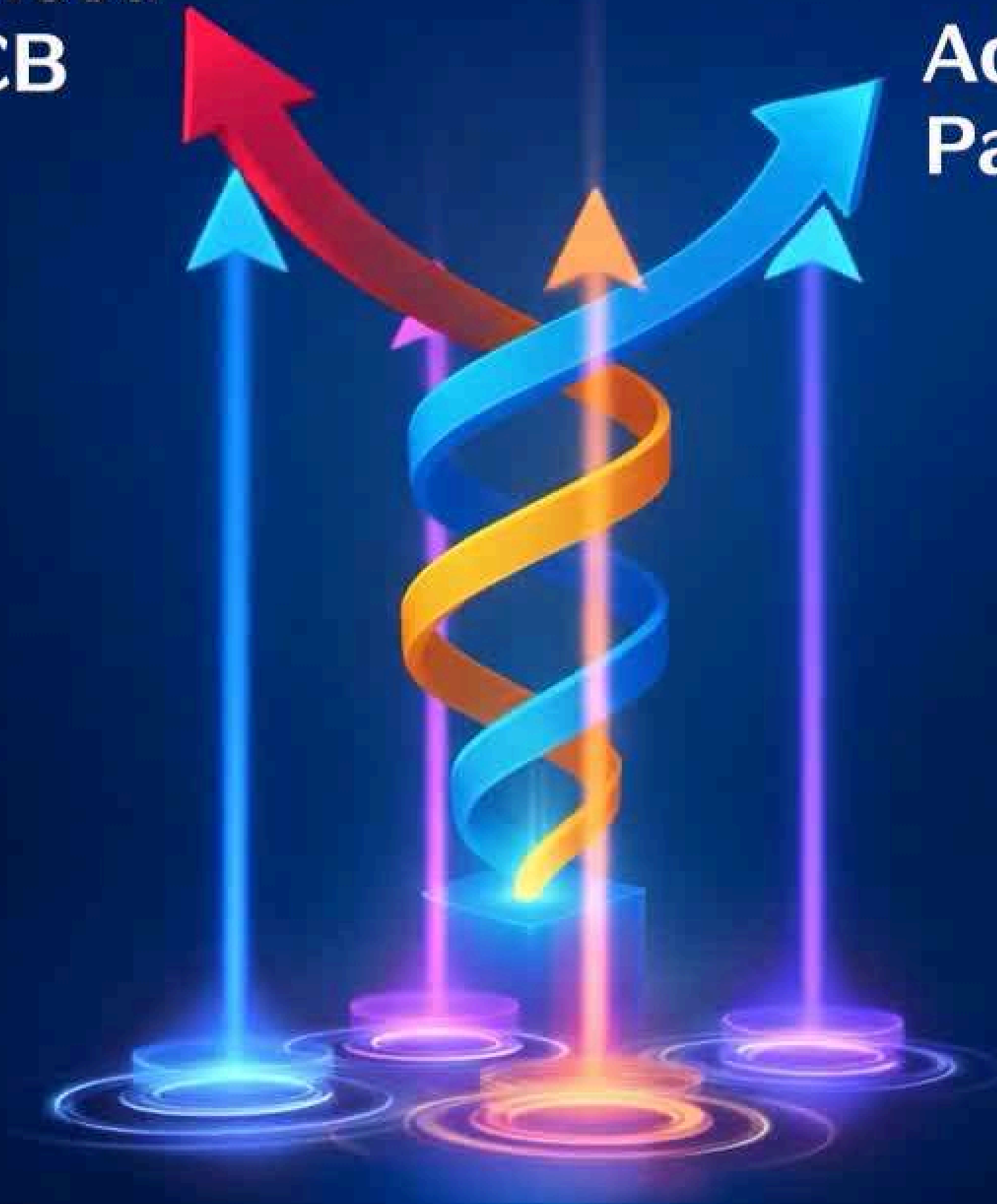
Edge AI

AI Infrastructure



**Advanced
PCB**

**Advanced
Packaging**



**Lamination, Peeling,
Bonding & Thermal
4 Engines Driving
the Future of Semi × PCB**



Market Momentum & CapEx Amplification Effect

Total AI Infrastructure CapEx by 2030

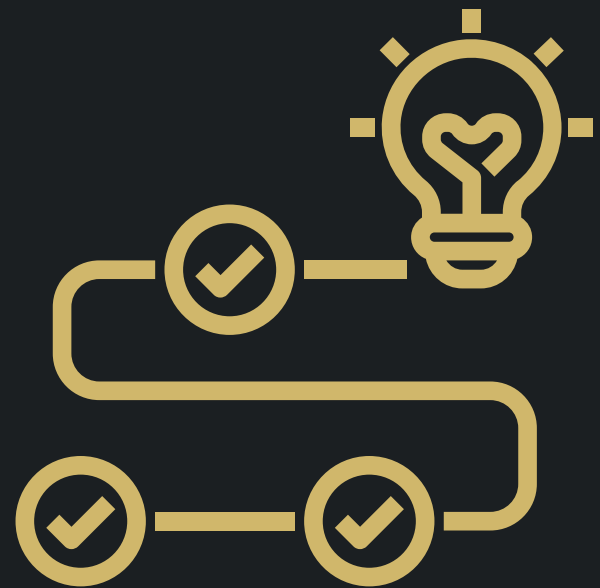
Barclays revised forecast: > USD 2 Trillion

Each 1 GW = USD 50-60 Billion Investment

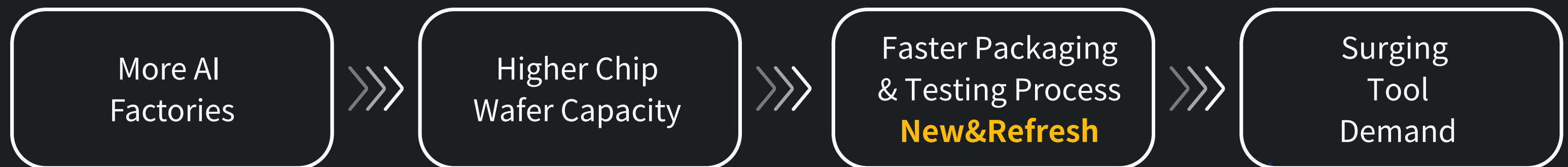
OpenAI X Nvidia 10 GW Project = USD\$500~\$600Billion

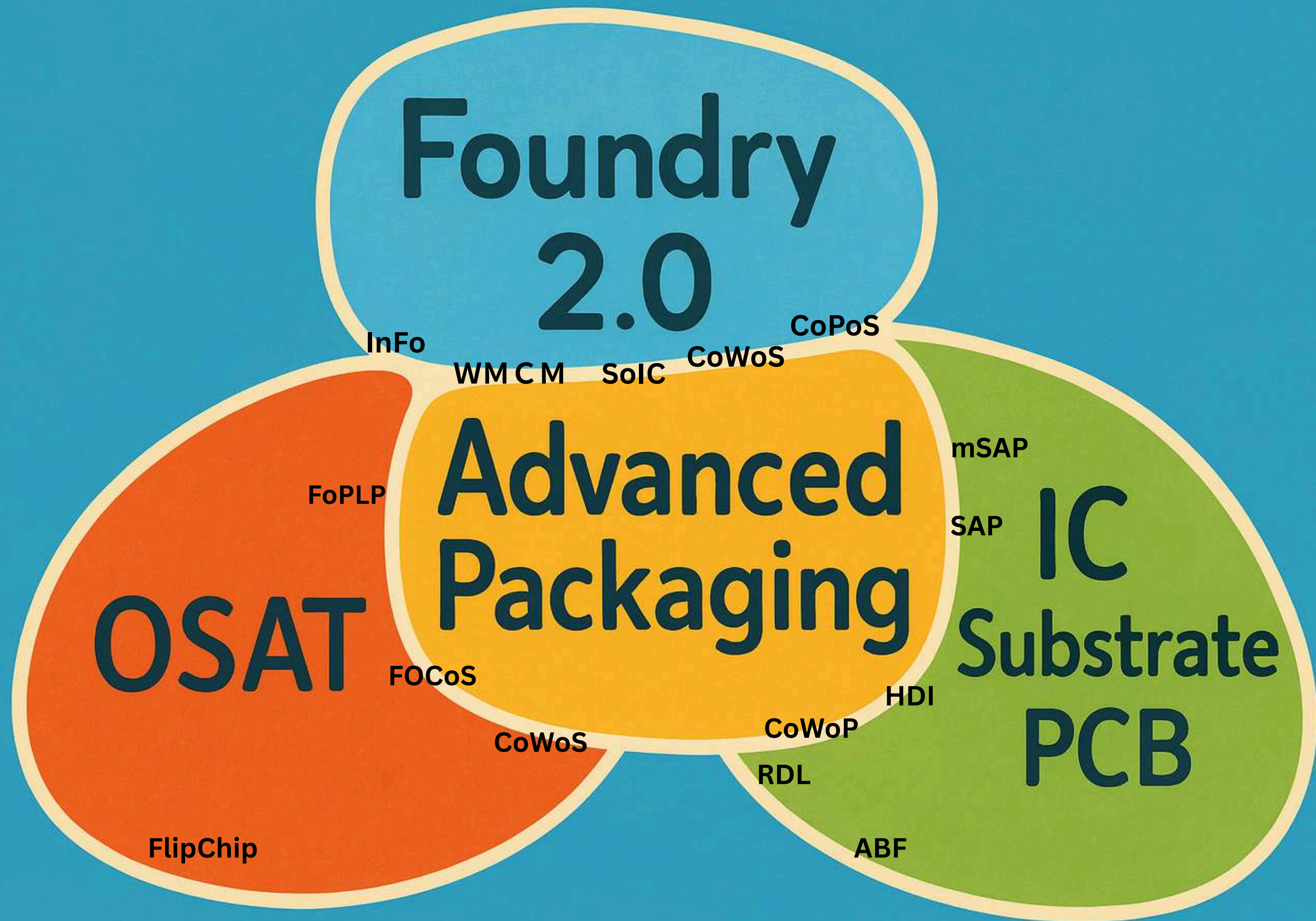
OpenAI X AMD 6 GW Project = USD\$300~\$360Billion

OpenAI X BroadCom 10 GW Project = USD\$500~\$600Billion

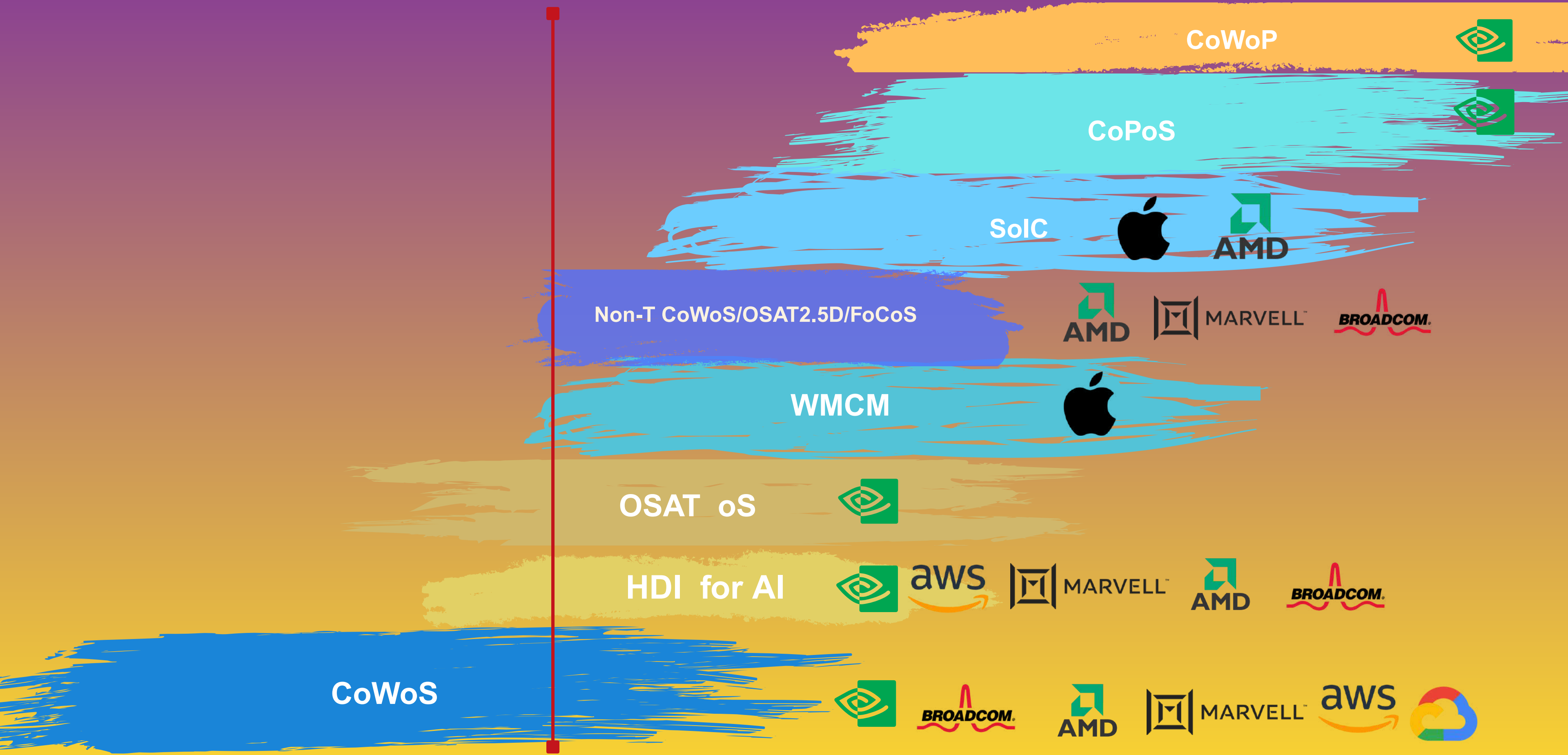


This creates an exponential multiplier effect for equipment investment

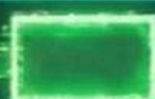
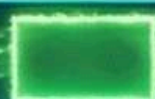




2023 2024 2025 2026 2027 2028 2029 2030



ADVANCED THERMAL PACKAGING APPLICATION MATRIX

Thermal Tech. Application (Oven)	CoW (Chip on Wafer)	oS (on Substrate)	OSAT oS	OSAT CoW	CoP (Chip on Panel)
1. After Cleaner (Drying)					
2. Pre-Cure					
3. Molding Cure					
4. PI Cure					
5. PI Bake					
6. LTHC Baking					
7. Pre-Baking					
8. De-Void					
9. Heat Sink Baking					
10. BSM Curing					
11. De-Warpage					
12. Annealing					



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A ***G2C+*** Alliance Company

Thank you for your attention
